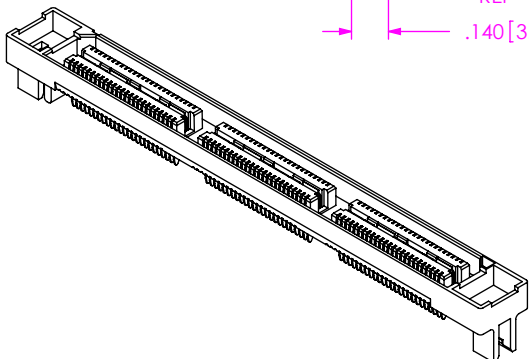
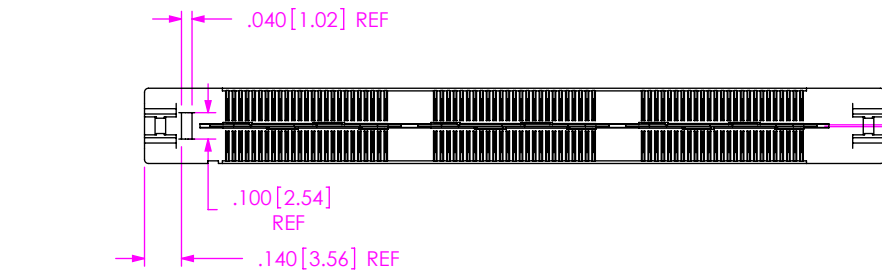
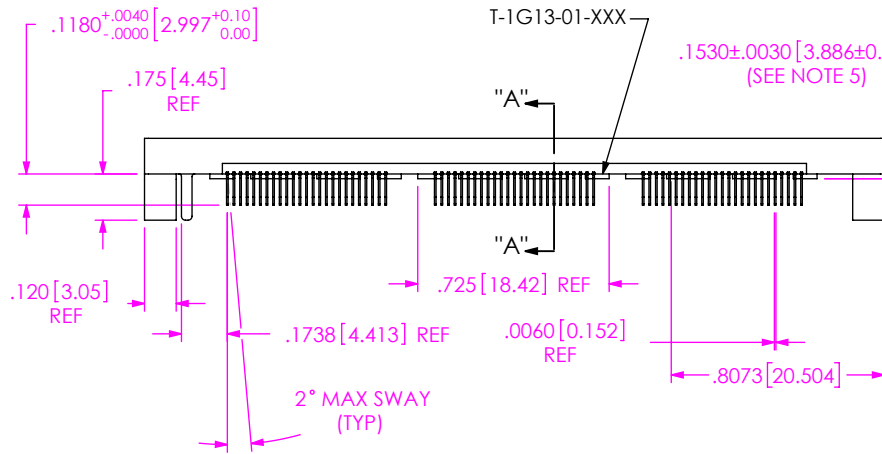
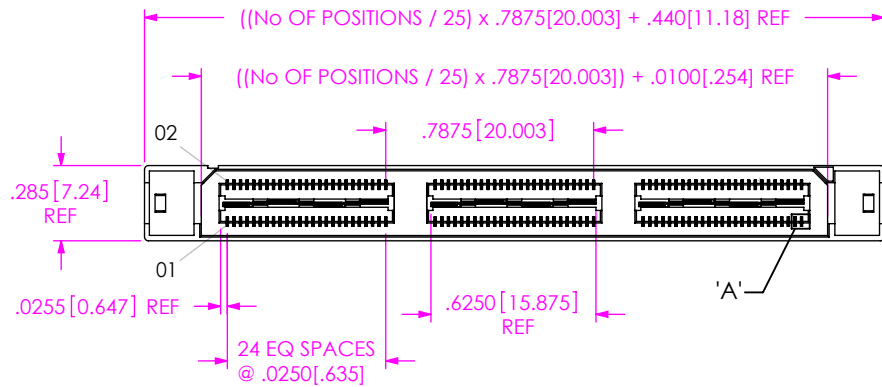


DO NOT SCALE FROM THIS PRINT



No OF POSITIONS	GND PLANE COPLANARITY	ASSEMBLY BOW
-025 THRU -075	.004 [.10]	.004 [.10]
*-100 THRU *-125	.005[1.27]	.005[1.27]

\* = SEE NOTE 12

QSS-XXX-01-XXX-D-EMX

No OF POSITIONS  
 -025, -050, -075,  
 \*-100, \*-125  
 (PER ROW)  
 \* = SEE NOTE 12

LEAD STYLE  
 -01: .1530[3.886]

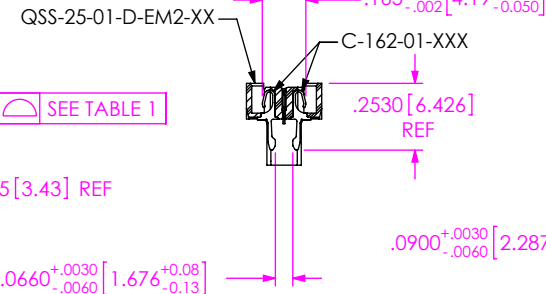
PLATING SPECIFICATION  
 -F: FLASH SELECTIVE GOLD, MATTE TIN TAIL  
 (USE C-162-XX-F & T-1G13-01-F)  
 -L: LIGHT SELECTIVE GOLD, MATTE TIN TAIL  
 (USE C-162-XX-L & T-1G13-01-L)  
 -H: HEAVY GOLD  
 (USE C-162-XX-H & T-1G13-01-G)  
 -STL: SELECTIVE GOLD, TIN/LEAD  
 (USE C-162-XX-STL & T-1G13-01-STL)  
 -FTL: FLASH SELECTIVE GOLD, TIN/LEAD  
 (USE C-162-XX-FTL & T-1G13-01-FTL)

EDGE MOUNT THICKNESS  
 -EM2: .064[1.63] ±.004 PCB  
 (USE QSS-25-01-D-EM2-XX & C-162-01-X)  
 -EM3: (USE QSS-25-01-D-EM3-XX  
 & C-162-02-X)

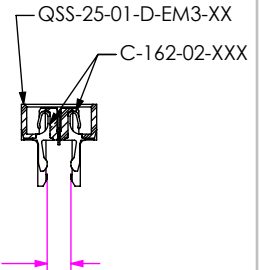
SEE NOTE 10

ROW SPECIFICATION  
 -D: DOUBLE (USE QSS-25-01-D-EMX-XX)

No OF BANKS



SECTION "A-A"  
 EDGE MOUNT THICKNESS  
 -EM2: .064[1.63] ±.004 PCB



SECTION "A-A"  
 EDGE MOUNT THICKNESS  
 -EM3:  
 SEE NOTE 10  
 (DIFFERENT AS SHOWN, OTHERWISE  
 SAME AS -EM2 PCB THICKNESS)

NOTES:

1. © REPRESENTS A CRITICAL DIMENSION.
2. CONTACT RETENTION: 6 OZ MIN.
3. GROUND PLANE RETENTION: 8 OZ MIN.
4. PARTS ARE MOLD TO POSITION.
5. MAX VARIANCE OF .002[.05].
6. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING.
7. NOTE DELETED.
8. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
9. SEE [http://www.samtec.com/processing/edgemt\\_tectalk/index.htm](http://www.samtec.com/processing/edgemt_tectalk/index.htm) FOR INFORMATION ON PROCESSING EDGE MOUNT PARTS TO BOARDS.
10. -EM3 & IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY.
11. NOTE DELETED.
12. AVAILABLE FOR EXISTING CUSTOMERS ONLY.

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN INCHES.  
 TOLERANCES ARE:  
 DECIMALS ANGLES  
 .XX: ±.01[.3] 2°  
 .XXX: ±.005[.13]  
 .XXXX: ±.0020[.051]

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MATERIAL: DO NOT SCALE DRAWING  
 INSULATOR: LCP, COLOR: BLACK  
 CONTACT: PHOS BRONZE  
 GROUND PLANE: PHOS BRONZE

SHEET SCALE: 1.375:1

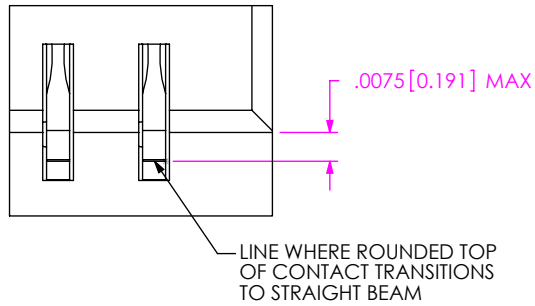
DESCRIPTION: .635mm EDGE MOUNT HS SOCKET ASSEMBLY

DWG. NO. QSS-XXX-01-XXX-D-EMX

BY: DEAN P 5/26/2000 SHEET 1 OF 2



520 PARK EAST BLVD, NEW ALBANY, IN 47150  
 PHONE: 812-944-6733 FAX: 812-948-5047  
 e-Mail: info@SAMTEC.com code: 55322



DETAIL 'A'  
SCALE 20:1

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DO NOT SCALE DRAWING

SHEET SCALE: 2:1



520 PARK EAST BLVD, NEW ALBANY, IN 47150  
 PHONE: 812-944-6733 FAX: 812-948-5047  
 e-Mail: info@SAMTEC.com code: 55322

DESCRIPTION: .635mm EDGE MOUNT HS SOCKET ASSEMBLY

DWG. NO. QSS-XXX-01-XXX-D-EMX

BY: DEAN P 5/26/2000 SHEET 2 OF 2